

Analysis of conducting materials by JY RF-GD-OES

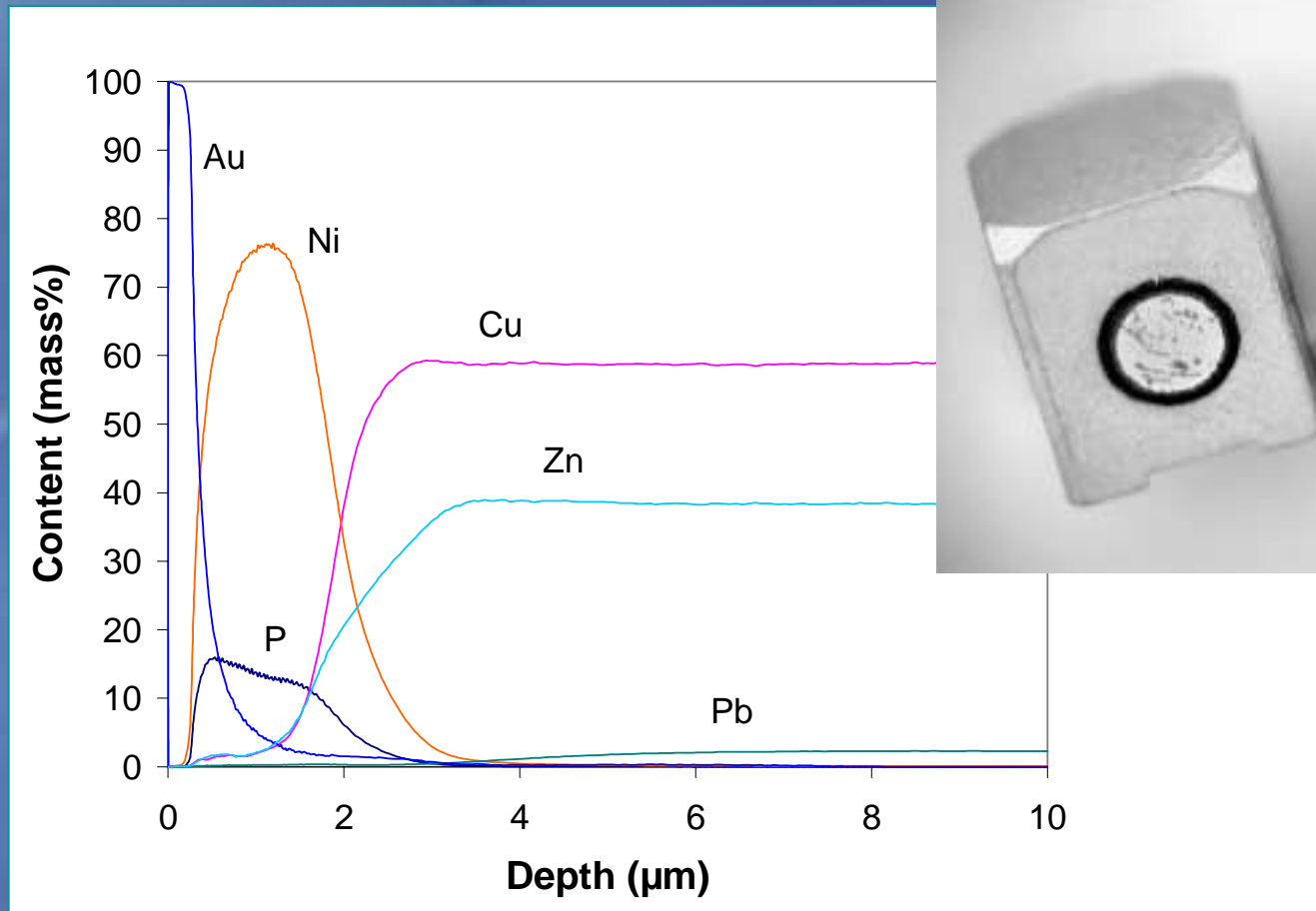
Christophe Deraed

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Introduction example



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Courtesy of EMPA

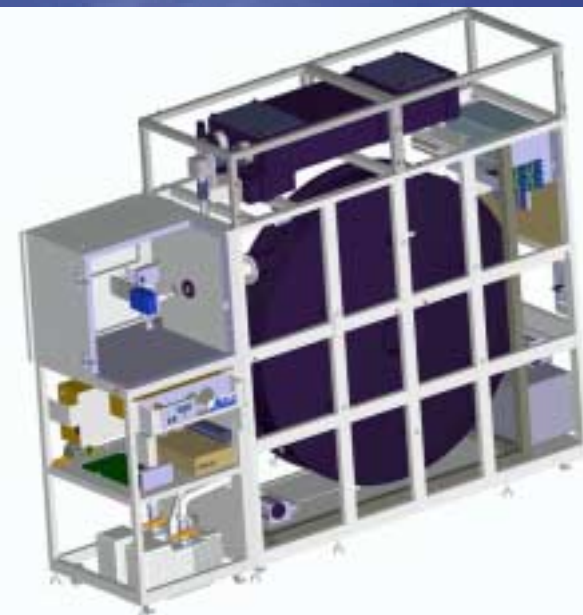


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Optical Spectrometer and RF powered Glow Discharge Source

- GD-PROFILER
 - 50cm Polychromator with up to 46 detectors
 - 64cm Monochromator
- GD-PROFILER HR
 - 1m Polychromator with up to 64 detectors
 - 1m Monochromator

Optical Spectrometer and RF powered Glow Discharge Source

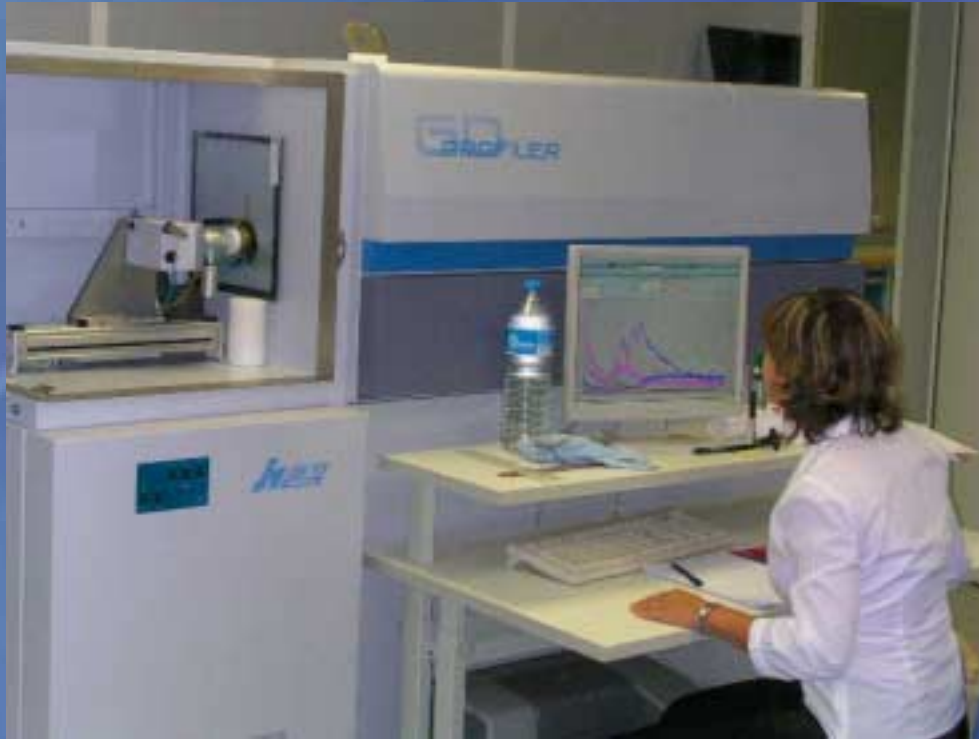


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Spacious analysis chamber



Large samples

Automatic cleaning

Centrelite for precise
positioning

GD-Profiler with a large (A4) sample
directly placed on the lamp

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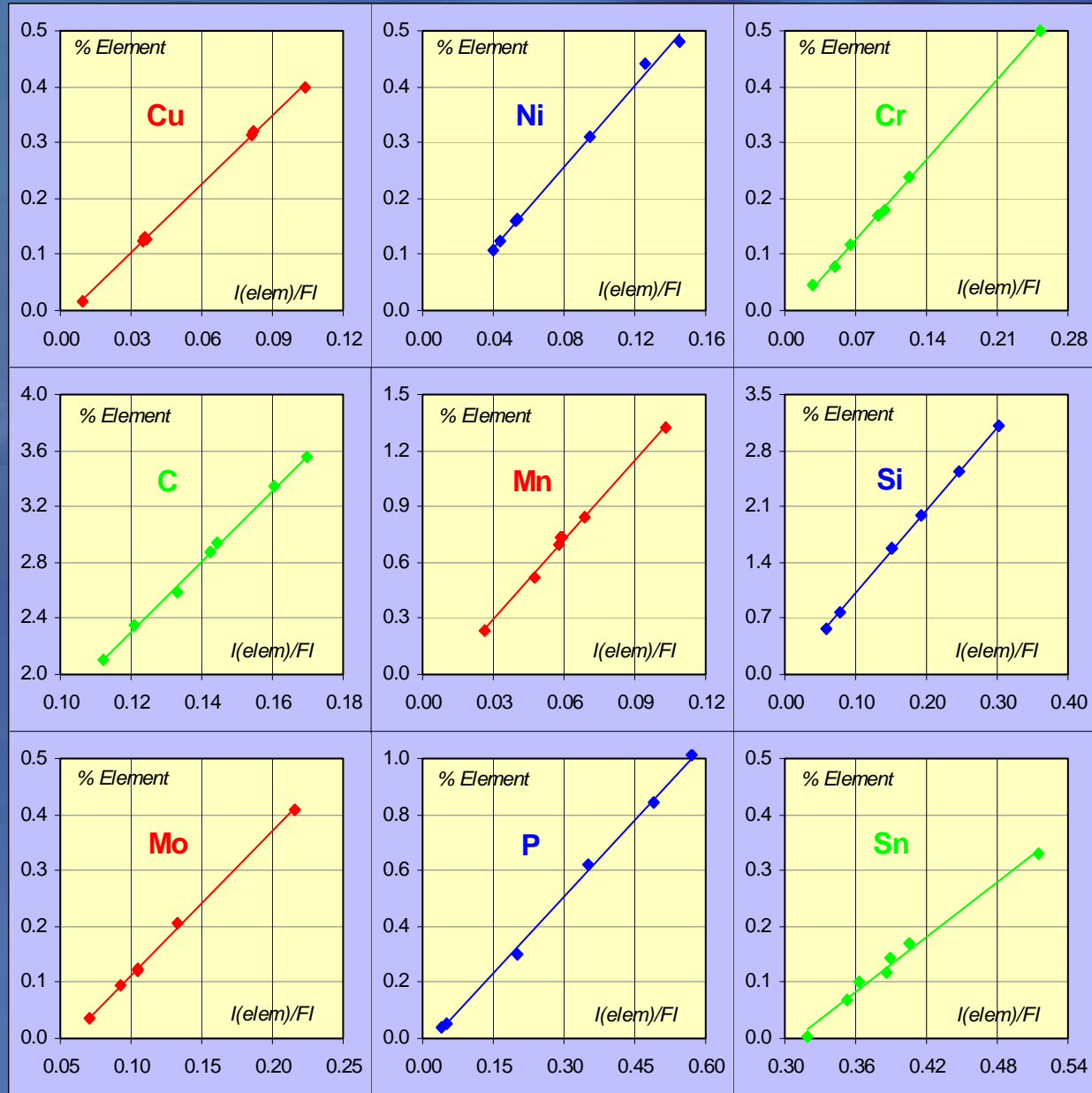
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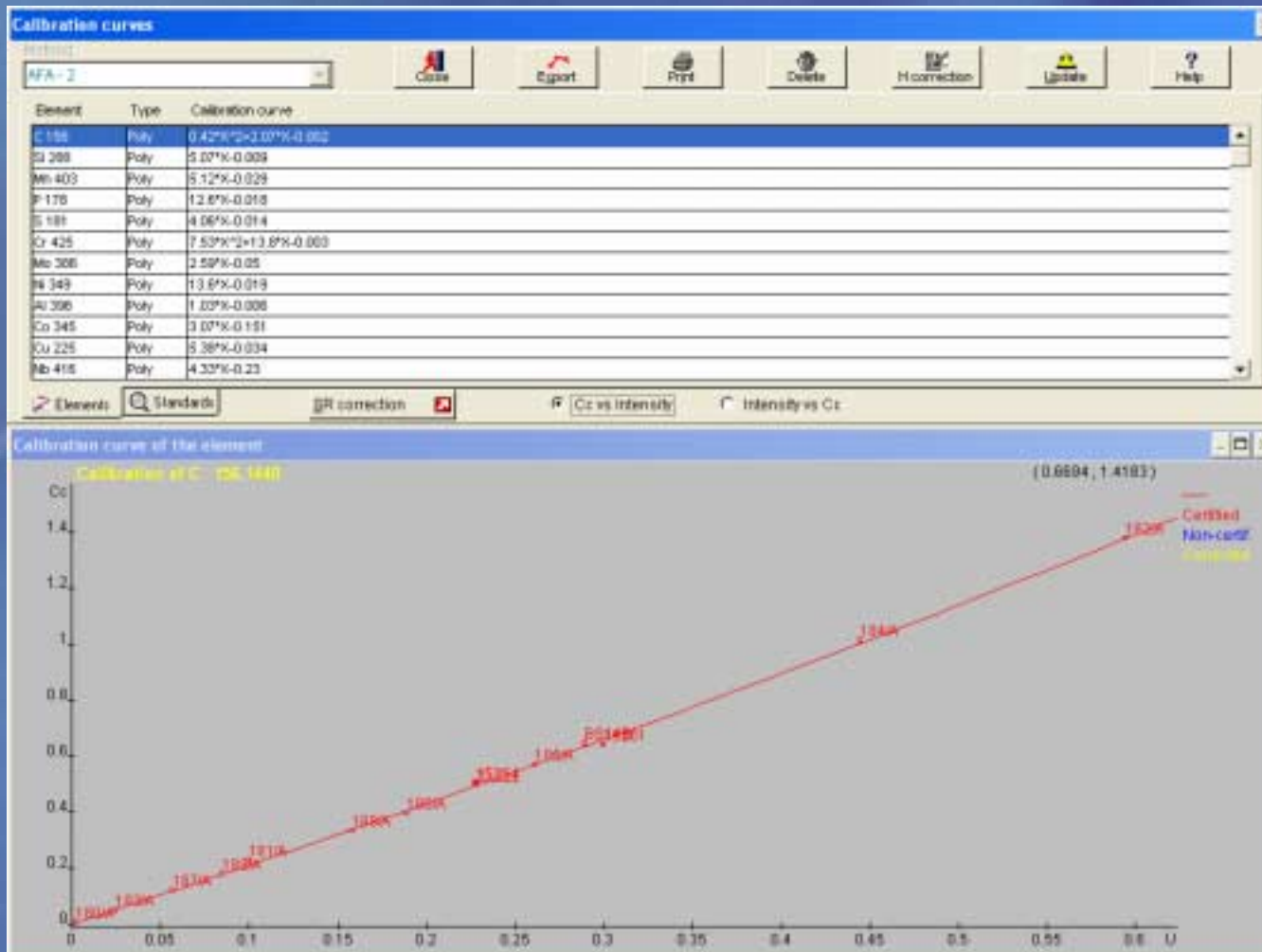
RF-GDOES CDP for conducting materials

- Quantitative Compositional Depth Profiling is like a series of ordinary bulk analyses repeated quickly on the same sample, same spot
 - With the addition of multimatrix and depth information
 - We first need to check whether bulk analysis is possible with RF-GDOES

Bulk analysis



Calibration curves



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Analytical methods

relative mode best for bulk analysis in most cases

Analytical function

$$\left(c_i / c_{maj} \right) = f \left([a_i]; I_i / I_{maj} \right)$$

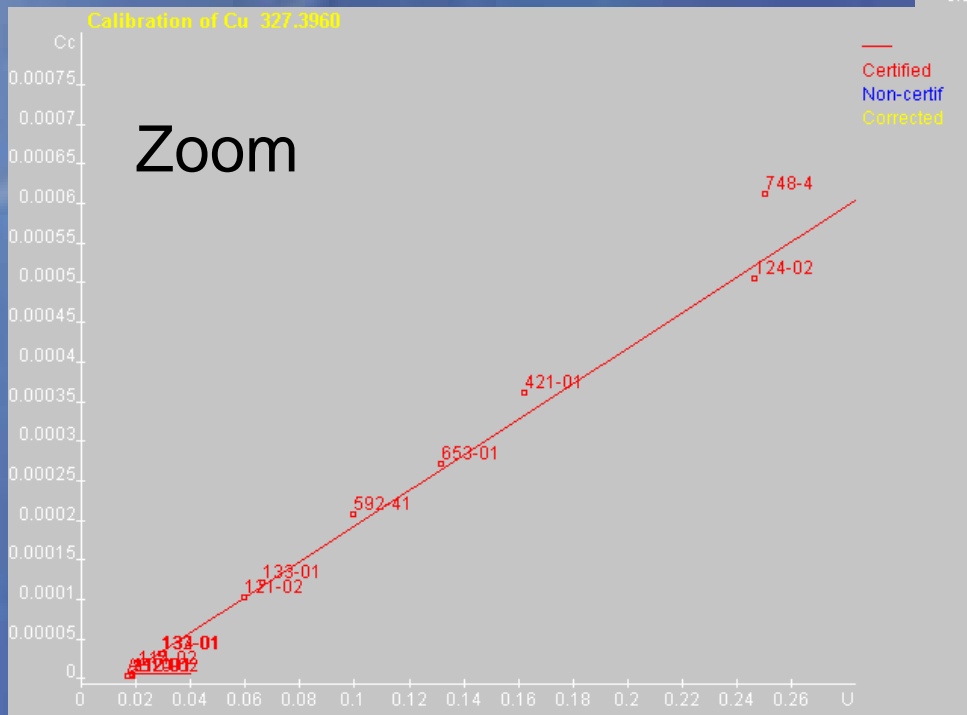
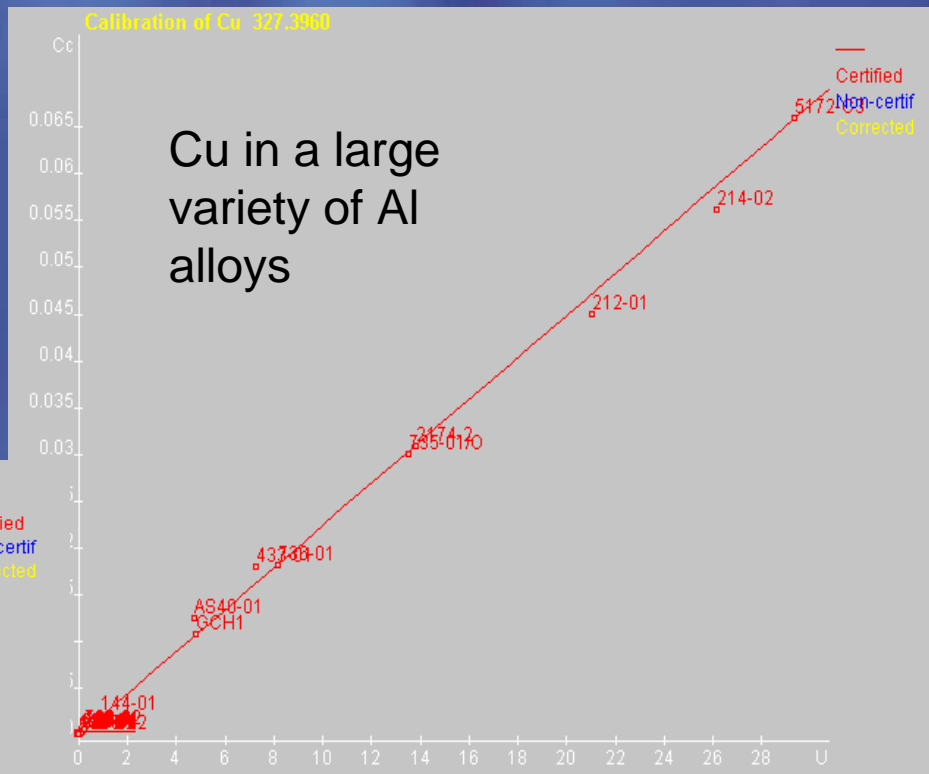
$$c_{maj}^{rel} = \frac{1}{1 + \sum c_i / c_{maj}}$$

Major element content

All elements except
major

$$c_i = \left(c_i / c_{maj} \right) \bullet c_{maj}^{rel}$$

Relative method Al matrix



Bulk Analysis: Steel

Element	Certified (mass %)	Measured (mass %)	SD (mass %)
Fe	70.8	71.3	0.01
Cr	17.3	17.5	0.05
Ni	9.2	9.1	0.04
Mn	1.38	1.38	0.01
Si	0.40	0.39	0.01
Cu	0.098	0.091	0.008
Mo	0.092	0.087	0.004
C	0.066	0.066	0.003
P	0.021	0.021	0.002
S	0.012	0.012	0.001

Table 2. RF-GD-OES Analysis of Stainless Steel 465/1

Bulk: Pure Pt data

Calibration curves of the method elements

Method: Metalor Platines - 0

Method type: Normal

Internal Std: Pt 225

Element	Type	Calibration curve	Estimated LD
Pt 225	Poly	-	
Ag 338	Poly	1.22*X-0.001	<1ppm
Au 268	Poly	12.5*X-0.006	1ppm
Co 387	Poly	3.96*X-0.002	<1ppm
Cr 425	Poly	0.165*X-2e-04	<1ppm
Cu 325	Poly	0.655*X-0.002	<1ppm
Fe 302	Poly	18.3*X-0.005	1ppm
Ir 204	Poly	9.79*X-0.015	2ppm
Mn 403	Poly	0.519*X-8e-04	<1ppm
Ni 362	Poly	0.646*X-0.001	1ppm
P 178	Poly	1.45*X-1e-04	1ppm
Pd 340	Poly	0.885*X-8e-04	<1ppm
Rh 343	Poly	1.28*X-7e-04	<1ppm
Sn 318	Poly	5.5*X-0.04	4ppm
Al 394	Poly	0.411*X-7e-04	<1ppm
B 250	Poly	0.04*X-6e-05	1ppm
Bi 307	Poly	9.65*X-0.056	5ppm
Ca 397	Poly	0.032*X-6e-04	<1ppm
Cd 361	Poly	5.59*X-0.004	<1ppm
Li 671	Poly	0.064*X-3e-04	<1ppm
Mg 285	Poly	0.241*X-1e-04	<1ppm
Pb 406	Poly	3.31*X-0.01	3ppm
Si 288	Poly	1.44*X-0.001	1ppm
Te 214	Poly	27.8*X-0.017	3ppm
Ti 369	Poly	0.904*X-0.002	1ppm
Zn 335	Poly	4.09*X-0.015	3ppm
Zr 469	Poly	3.72*X-0.037	3ppm

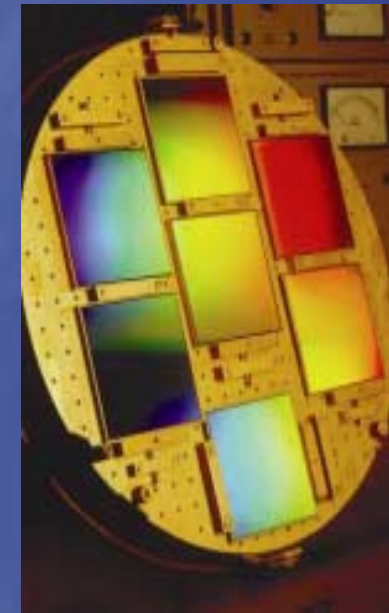
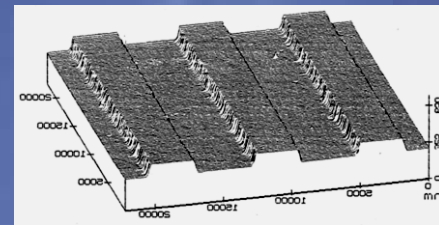
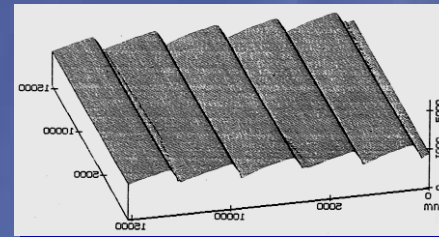
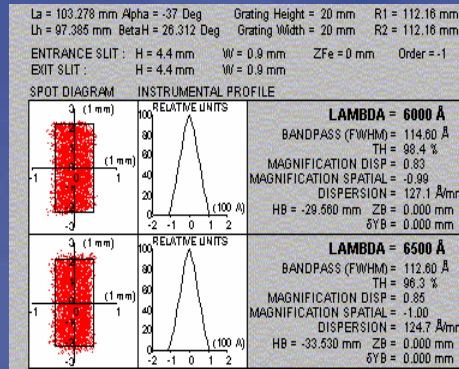
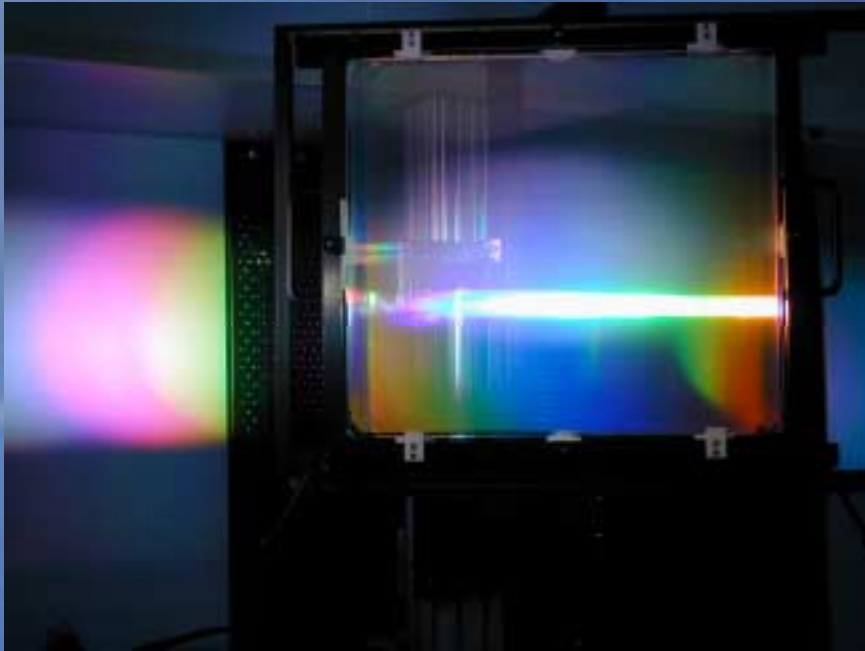
Most elements are very good

Bi 307 : special care required in sample handling (line close to an OH molecular band)

Bulk analysis

- Bulk analysis of conducting material is possible with RF-GDOES
 - The quality of CDP will most likely not be better than the quality of Bulk analysis
 - A few important features

Optics : Diffraction gratings



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HJY Very High Quality Optical Components



Up to 64 channels (on HR).

Blazed UV grating corrected for aberrations.

Paschen Runge mounting

Additional Flat field mount with IR grating for alkali

Mask for flexibility

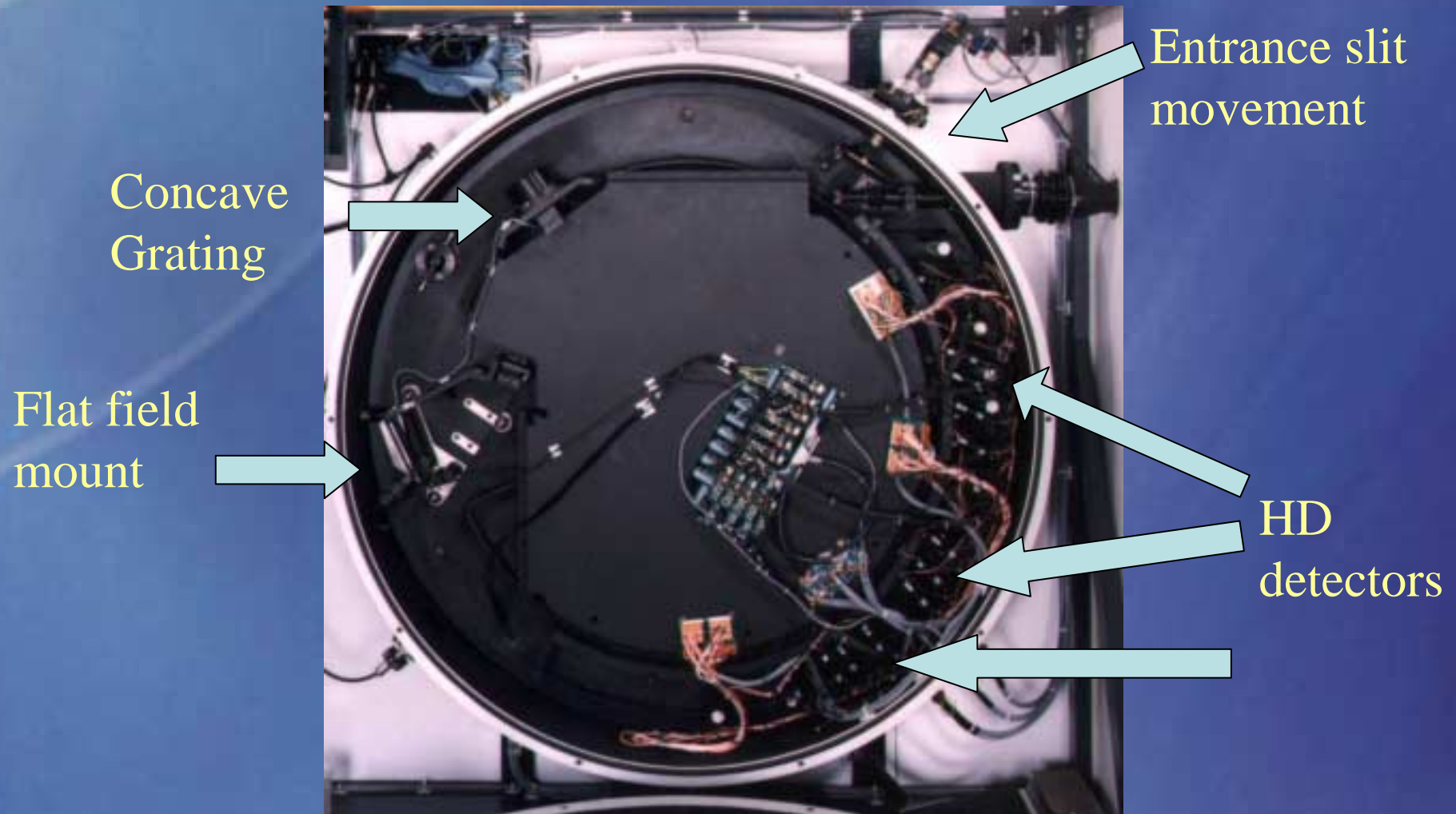
Very High Resolution

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High resolution poly (GD-Profiler HR)

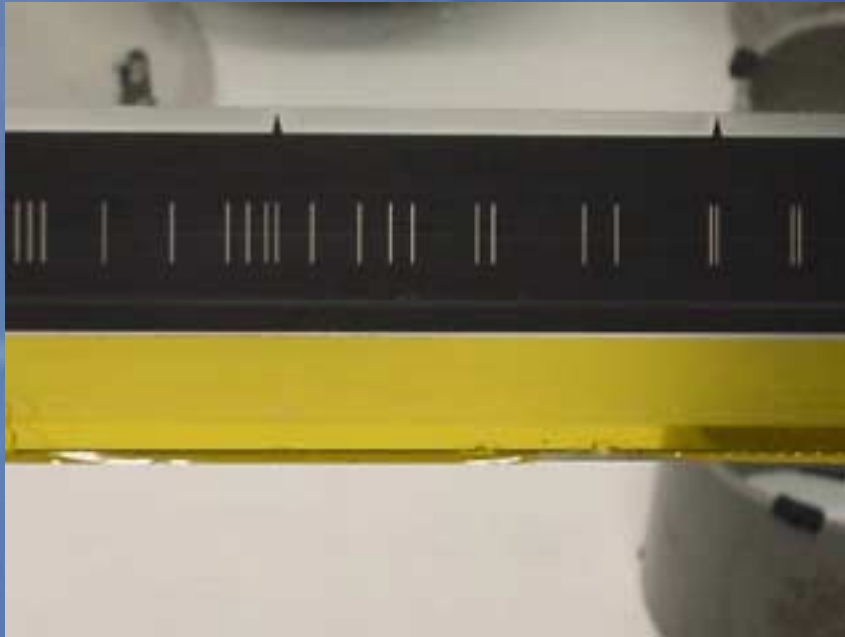


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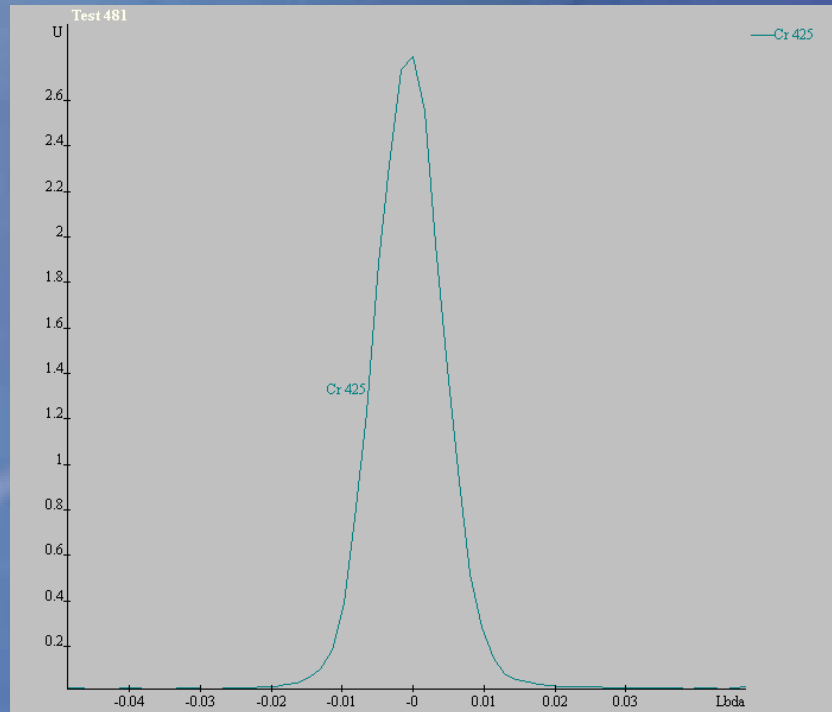
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Flexibility of line selection



- Partial view of the mask with the secondary slits.
- The full mask is 1.2m long. Wavelengths positions are corrected for temperature (poly is thermoregulated).
- Mask produced by electrodeposition. Very high dimensional precision. Pure Ni with a thin Cu layer on top of it oxidized for darkness.
- Only the lines of interest will be kept open, others will be covered. On site modification or extension is possible.

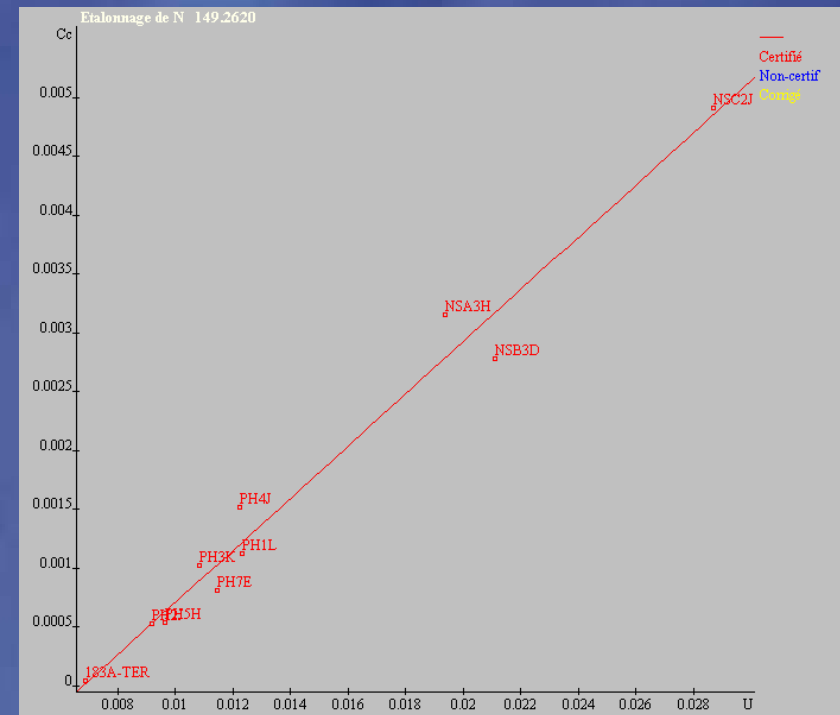
Resolution and sensitivity



Line profile of Cr (1 order) :

Resolution 12pm (on HR)

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Calibration of N in steels

BEC 200ppm, LQ 10ppm

Principle of Polyscan

Principle of emission spectrometry

Spectral scanning devices

Floating quartz plate

Entrance slit movement following the Rowland circle

Amplitude of the spectrum exploration :

0.1 nm 2 nm without defocalisation

It may be advantageous to explore the spectrum on either side of the line, either over a short distance, to check spectral alignment, or over a medium distance, to assess the influence of the emission background, or over a larger distance to use other analytical lines.

Let's remember that the radiation from a slit contains both the analytical line and the spectral background, made up of the continuous background and the wings of the near and intense lines. When the background is not corrected, the analysis result is erroneous. To analyze traces, this error should be eliminated by measuring the intensity on either side of the line to measure the background and deduct it.

To explore the spectrum, it is simpler to move the entrance slit, either optically or mechanically. This way, the spectrum can be scanned simultaneously around all the analytical lines of the optical programme.

To optically scan the image of the entrance slit, a parallel-face blade is placed behind the slit. By rotating the blade, the image of the slit moves. However, this rotation defocuses the system and only allows limited spectral explorations.



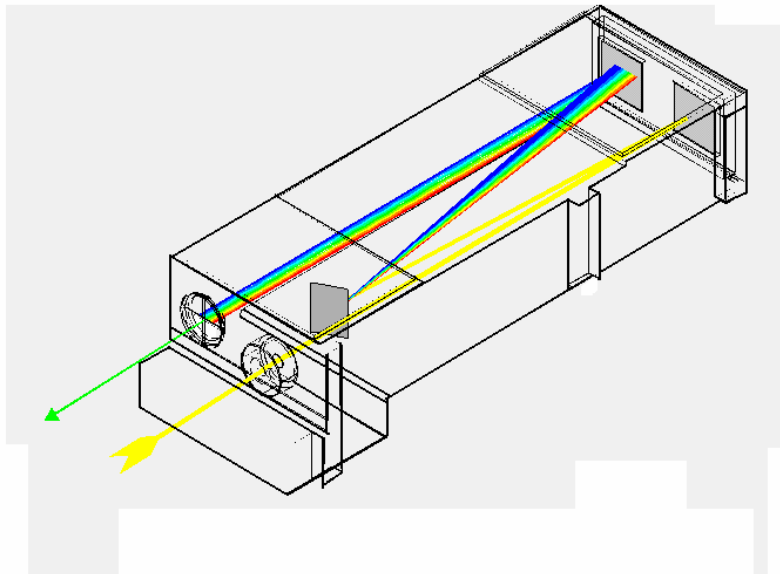
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Applicable to BULK only

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Direct observation with a monochromator

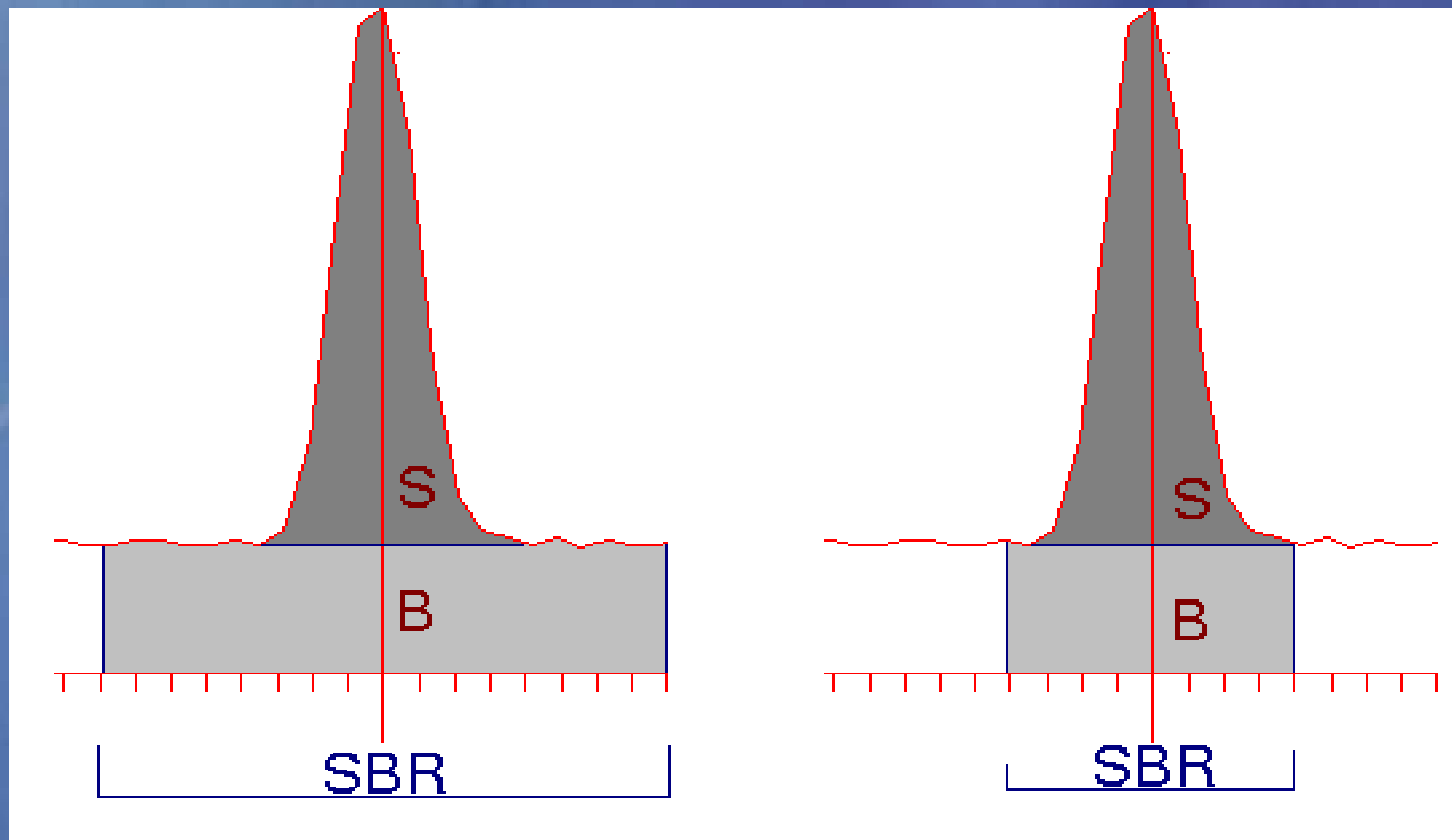


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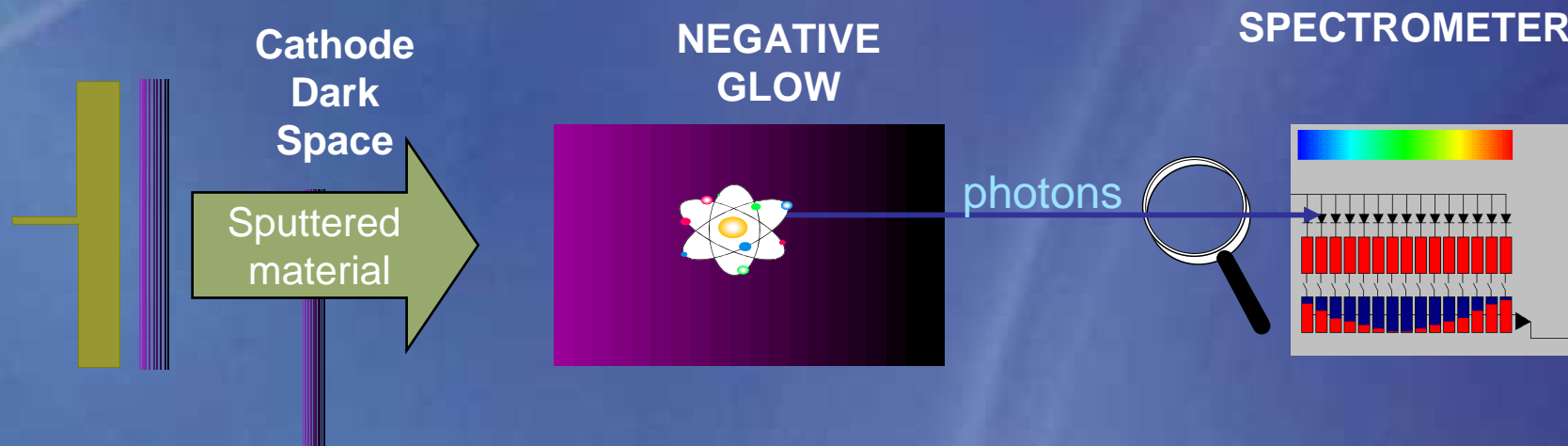
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*Signal / Background Ratio
larger for smaller spectral band pass*



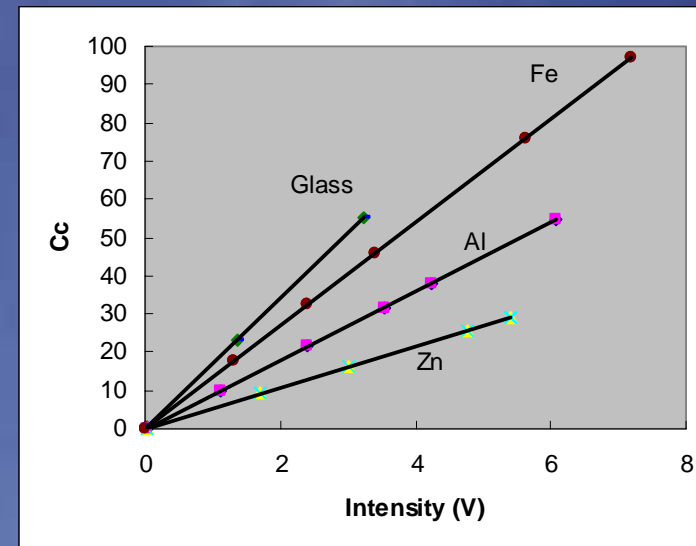
Three basic processes

- Erosion (sputtering)
 - Ion Bombardment
 - Secondary Electron Emission
 - Particle erosion
- Excitation (emission)
 - Collision
 - Excitation
 - Light Emission
- Detection and light collection



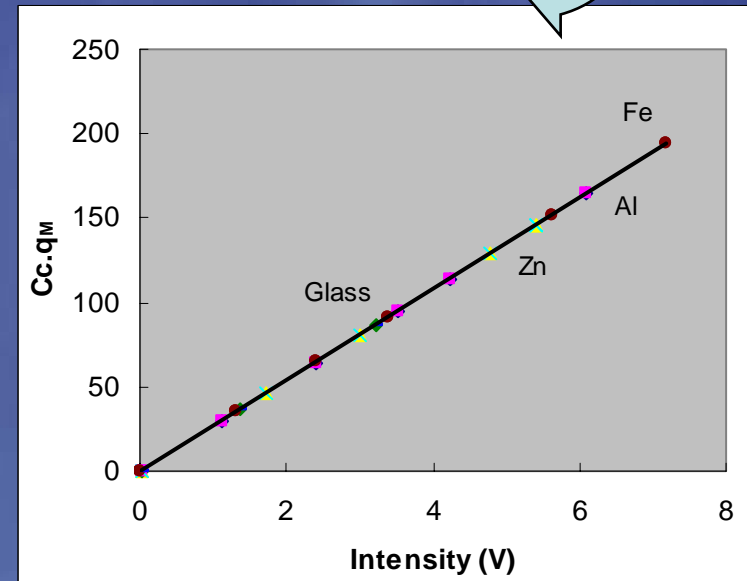
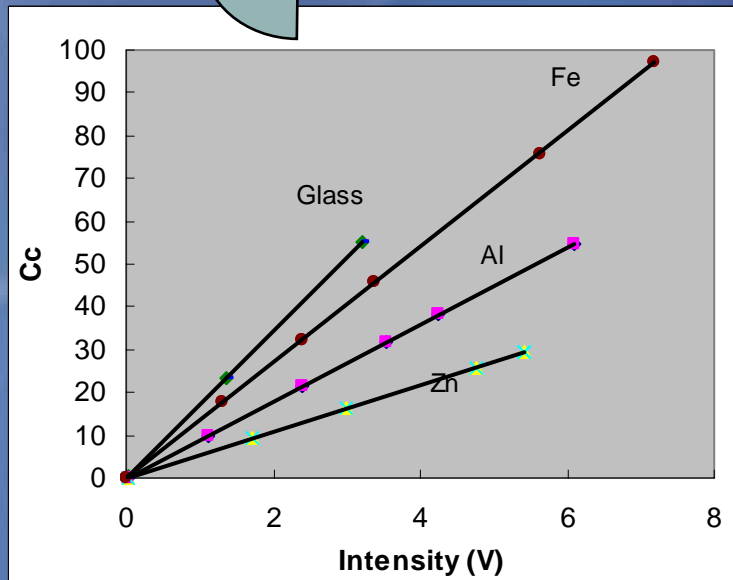
CDP Calibration

- Calibration : we want to create a functional relationship between the observed signals and a elemental composition of the sample
- The detector actually records the light emitted by the plasma, the sample itself does not emit any light.
- If we neglect this we would get in the best case the following result
- each type of material leads to one straight line
- in worst case we have a calibration cloud



Sputtering rate correction

We can calibrate and calculate the depth

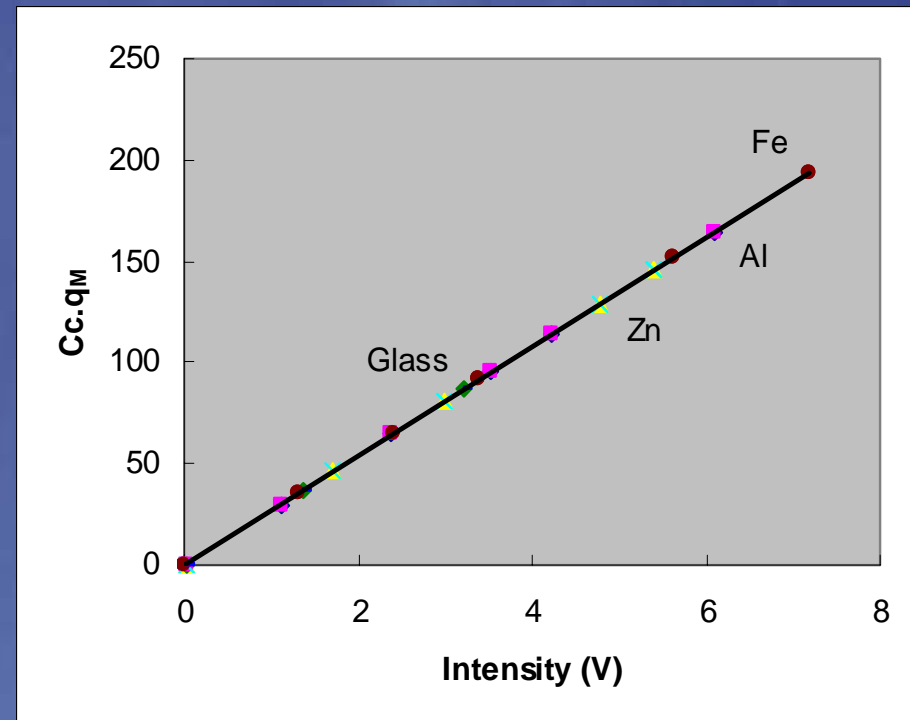


Composition of the plasma

- The plasma contains mainly argon, the discharge carrier gas.
- Constituents of the plasma other than argon should come from the sample through sputtering
- A steady process of sputtering material and pumping it away
- The elemental composition of the plasma is proportional to the product of sputtering rate q and the composition of the sputtered sample surface c_i
- The composition of the plasma is equivalent to the composition of the samples surface multiplied by the sputtering rate

The 'cq' calibration line

- the analytical curve gives the concentration corrected by the sputtering rate as a function of the measured intensities
- For a given concentration : if the sputtering rate increases, the observed signal increases.
- If the concentration increases at the sample surface at constant sputter rate the signal will increase



Normalisation to 100%

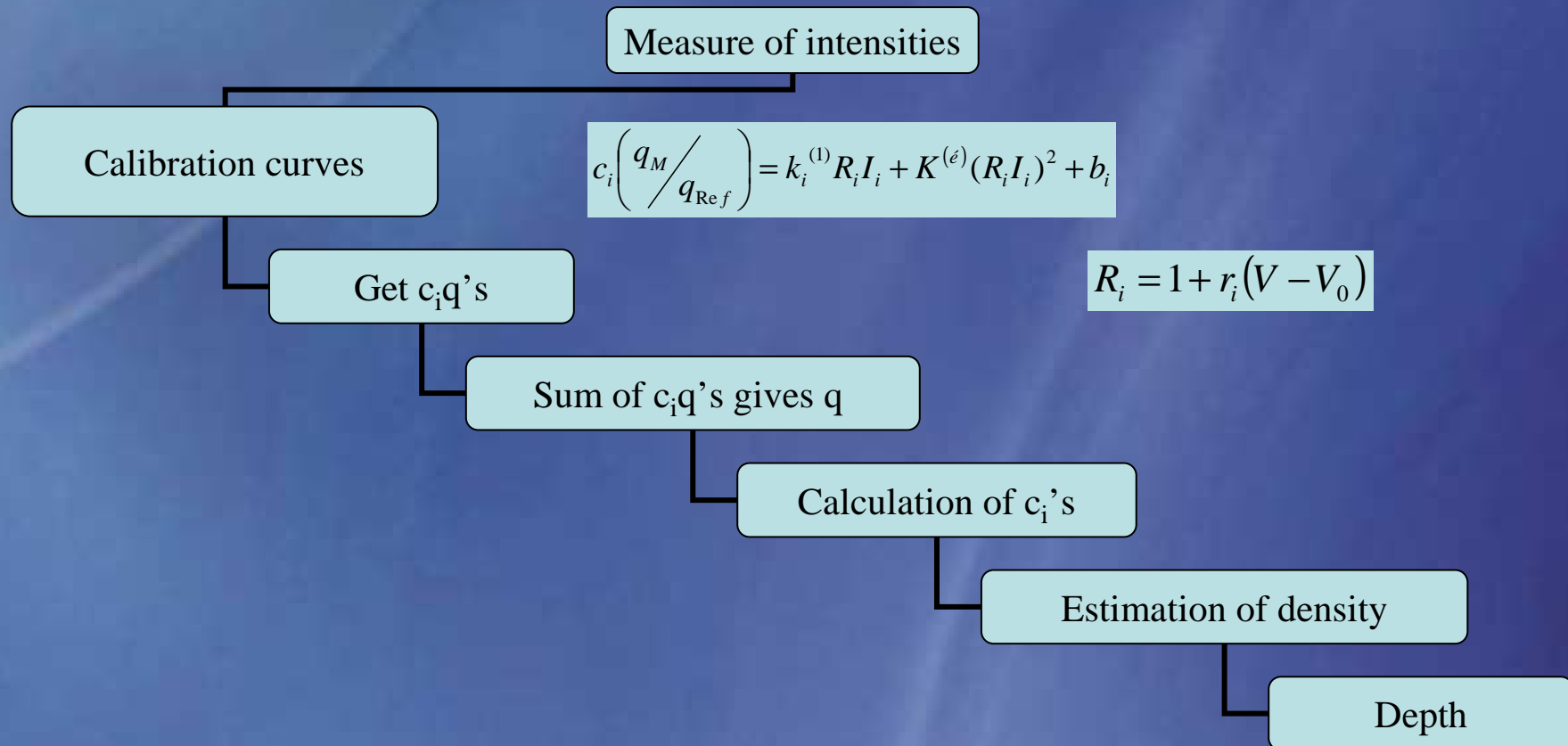
- We need to know the chemical composition of the sample and not so much the composition of the plasma.
- If we assume all elements are analysed, the sum of all elements must be 100%
- Now we know the sputter rate
- and can calculate the elemental content in the sample

• $\sum C_i = 1;$

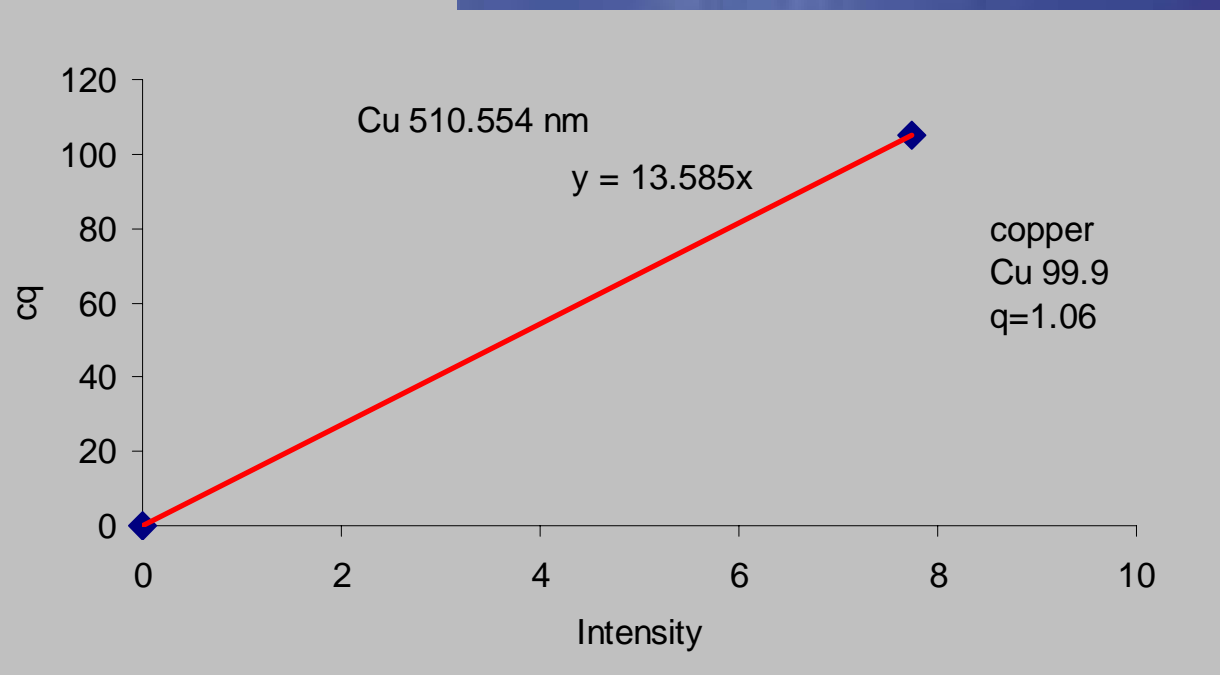
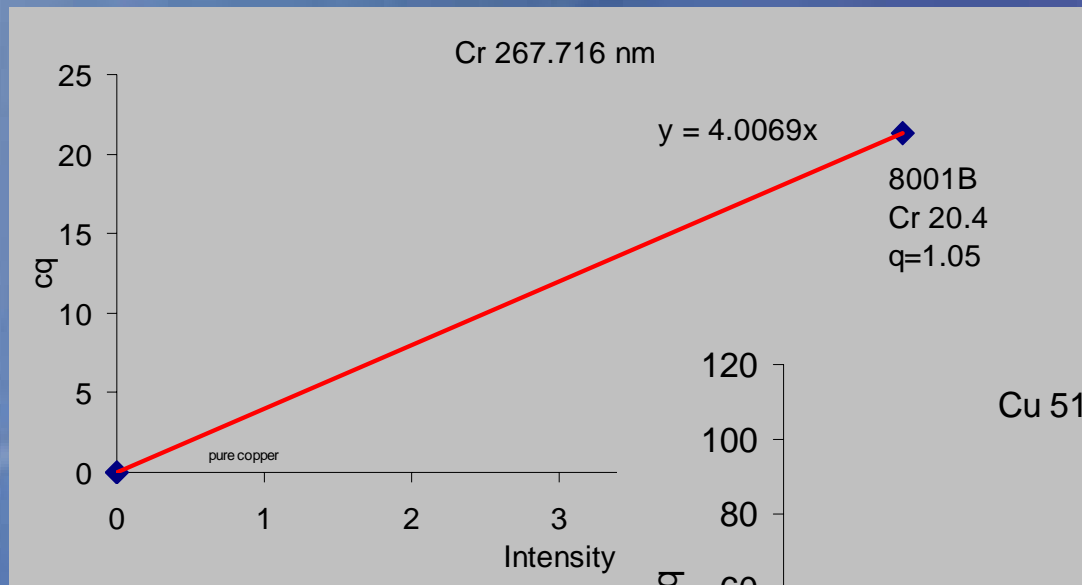
$$\sum C_i q = (\sum C_i) q = q$$

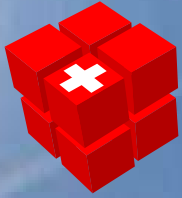
$$C_i = \frac{(C_i q)}{q}$$

CDP : the quantification chain

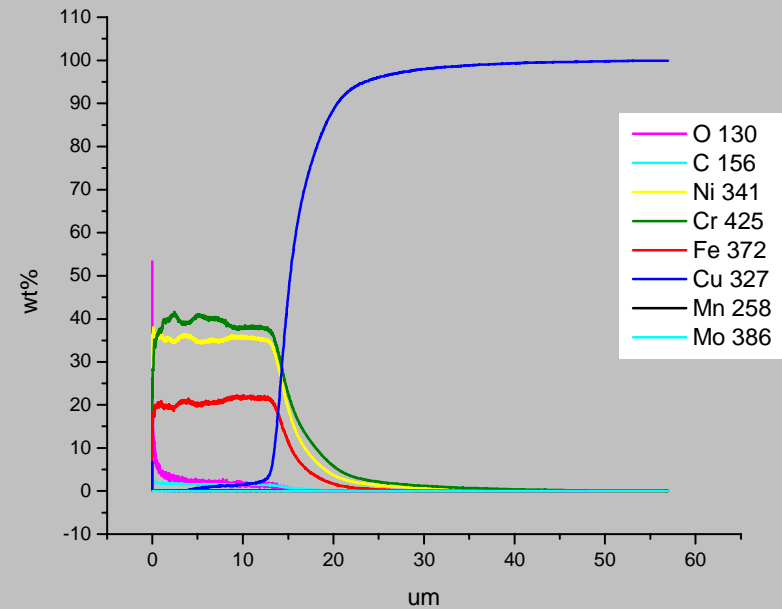
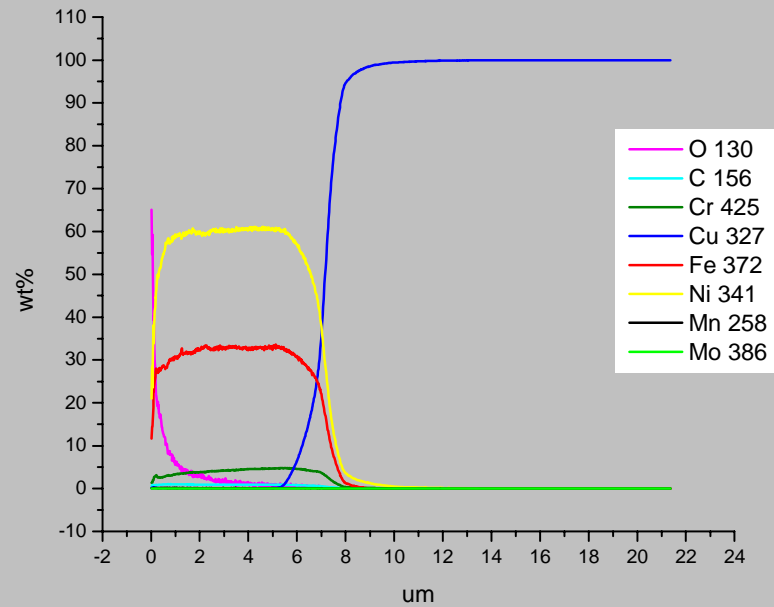


Calibration curve: simple





Application electrochemical deposition of steel on Cu



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Analytical methods

relative calibration mode for CDP

Basic idea :

For many applications we do not need a real multi-matrix calibration : cladding, heat treatment, Oxidisation...

It is sufficient to use the 'virtual' calibration mode for all elements but the major. Only the major is calibrated in the 'cq' mode.

Analytical methods

relative mode

$$\left(c_i / c_{maj} \right) = f \left([a_i]; I_i / I_{maj} \right)$$

$$c_{maj}^{rel} = \frac{1}{1 + \sum c_i / c_{maj}}$$

$$c_i = \left(c_i / c_{maj} \right) \bullet c_{maj}^{rel}$$

'cq' mode

$$c_{maj} q_{rel} = f \left([a]; [I_{maj}] \right)$$

$$q = \frac{c_{maj} \cdot q}{c_{maj}^{rel}}$$

Analytical methods

relative calibration mode for CDP

Advantages :

Only few CRM with known sputtering rate are needed.

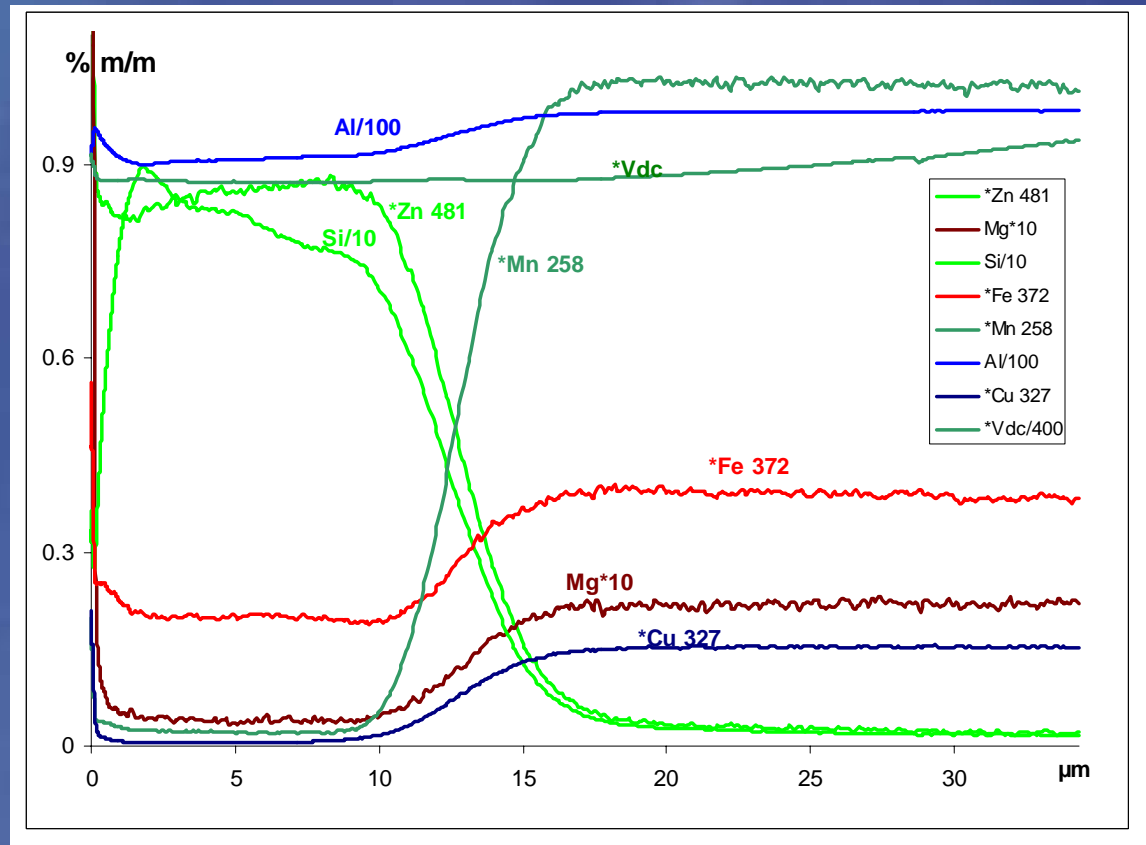
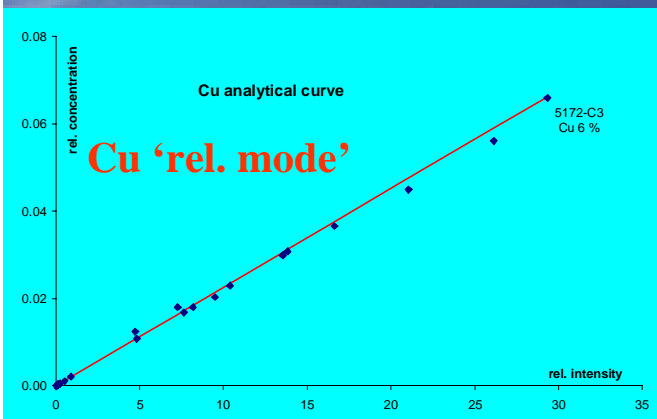
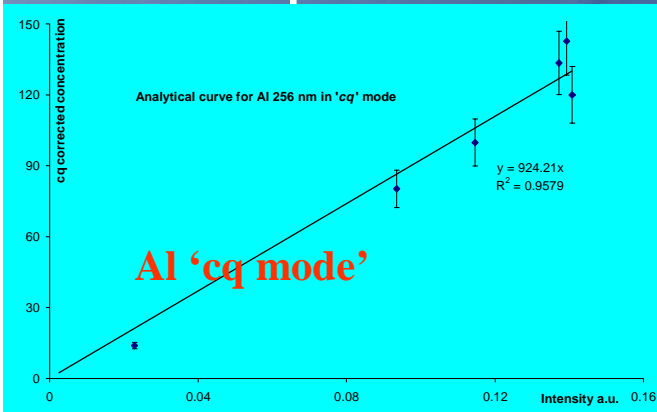
More CRM can be included in the calibration

The major source of uncertainty is excluded from the calculation of the chemical content

Analytical methods

relative calibration mode for CDP

example : Cladded aluminium sheet

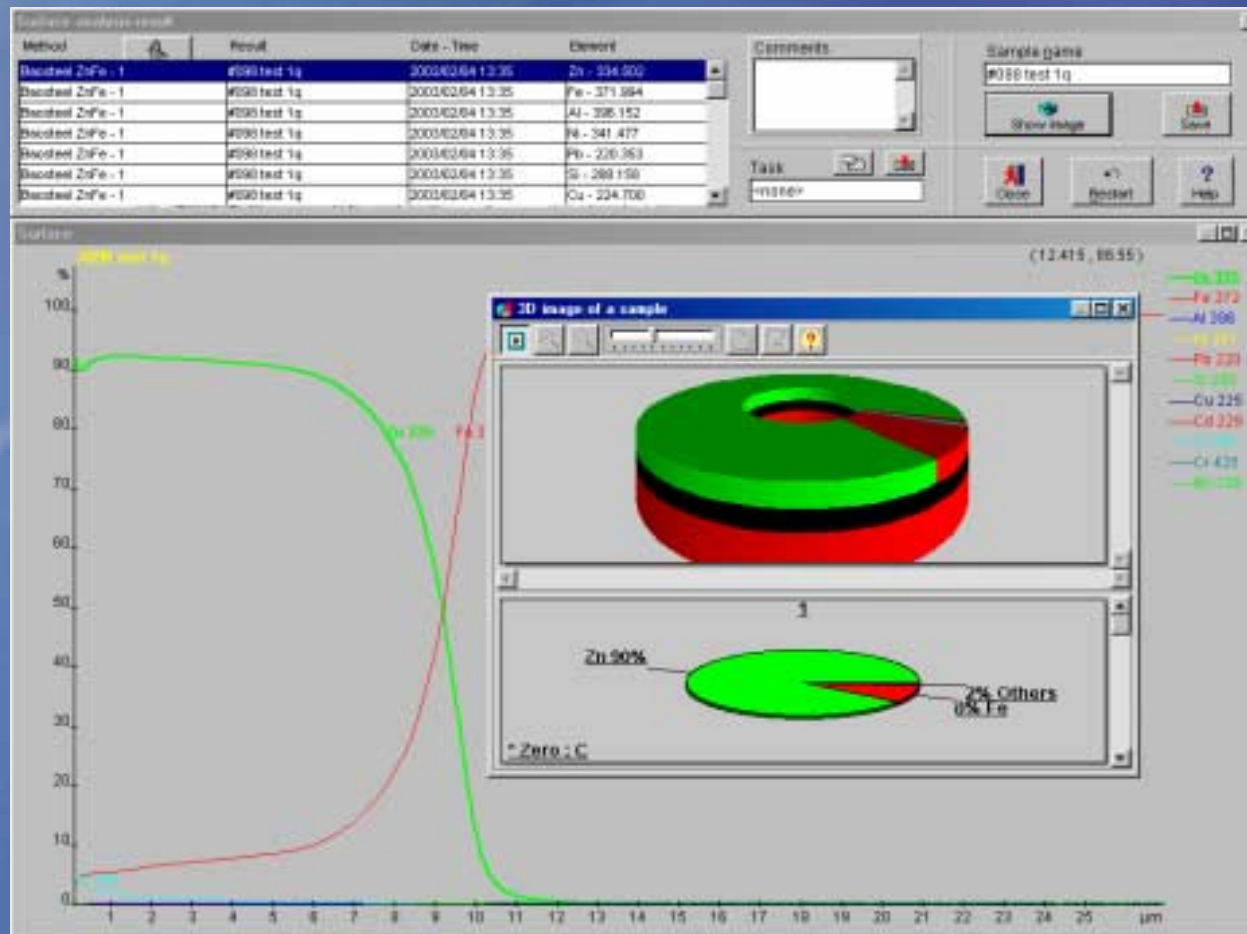


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Depth profiling: ZnFe coating on Steel



Control of coating weights

Control of process defects

NEWS NEWS

ISO 16962

GD recent books

Marcus:

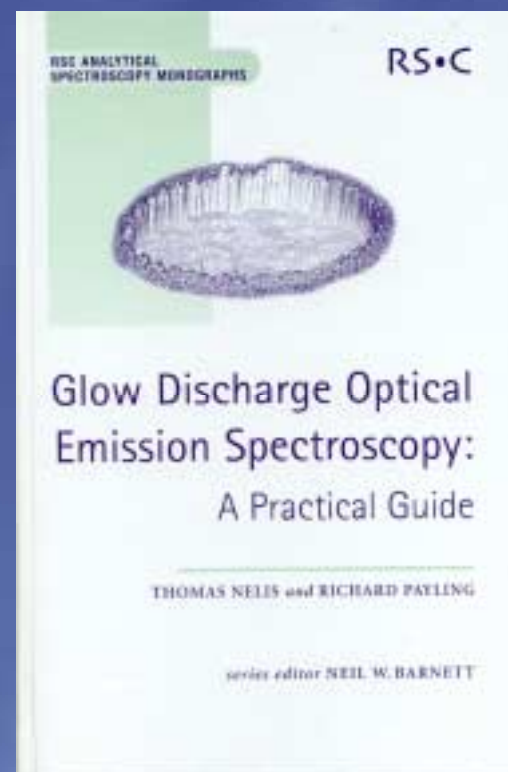
“Glow Discharge Plasmas in
Analytical Spectrometry”

Wiley, November 2002

Nelis and Payling:

“Practical Guide to Glow
Discharge Optical Emission
Spectroscopy”

Royal Society of Chemistry,
Cambridge, 2004



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This is the end

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